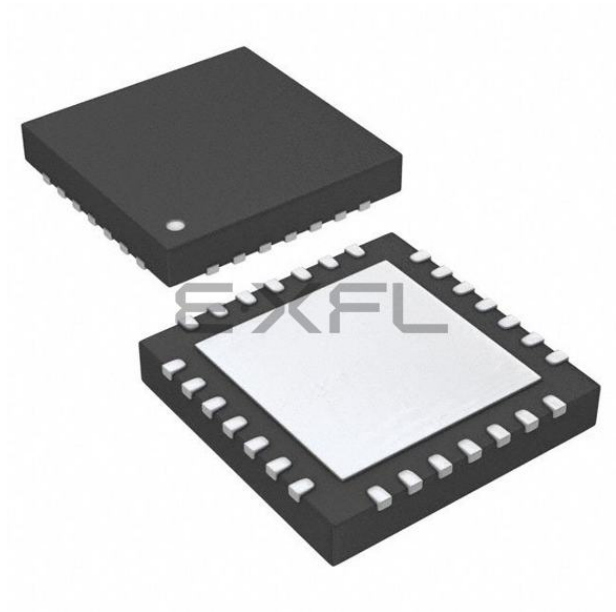

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf722at-i-mv

3.1 MCLR

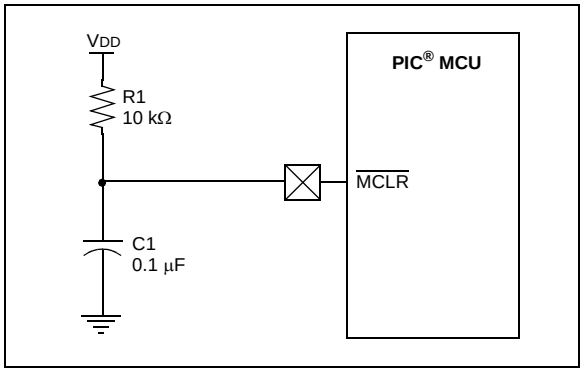
The PIC16(L)F722A/723A has a noise filter in the MCLR Reset path. The filter will detect and ignore small pulses.

It should be noted that a Reset does not drive the MCLR pin low.

Voltages applied to the pin that exceed its specification can result in both MCLR Resets and excessive current beyond the device specification during the ESD event. For this reason, Microchip recommends that the MCLR pin no longer be tied directly to VDD. The use of an RC network, as shown in Figure 3-2, is suggested.

An internal MCLR option is enabled by clearing the MCLRE bit in the Configuration Word register. When MCLRE = 0, the Reset signal to the chip is generated internally. When the MCLRE = 1, the RE3/MCLR pin becomes an external Reset input. In this mode, the RE3/MCLR pin has a weak pull up to VDD. In-Circuit Serial Programming is not affected by selecting the internal MCLR option.

FIGURE 3-2: RECOMMENDED MCLR CIRCUIT



3.2 Power-on Reset (POR)

The on-chip POR circuit holds the chip in Reset until VDD has reached a high enough level for proper operation. A maximum rise time for VDD is required. See **Section 23.0 "Electrical Specifications"** for details. If the BOR is enabled, the maximum rise time specification does not apply. The BOR circuitry will keep the device in Reset until VDD reaches VBOR (see **Section 3.5 "Brown-Out Reset (BOR)"**).

When the device starts normal operation (exits the Reset condition), device operating parameters (i.e., voltage, frequency, temperature, etc.) must be met to ensure operation. If these conditions are not met, the device must be held in Reset until the operating conditions are met.

For additional information, refer to Application Note *AN607, Power-up Trouble Shooting* (DS00607).

3.3 Power-up Timer (PWRT)

The Power-up Timer provides a fixed 64 ms (nominal) time-out on power-up only, from POR or Brown-out Reset. The Power-up Timer operates from the WDT oscillator. For more information, see **Section 7.3 "Internal Clock Modes"**. The chip is kept in Reset as long as PWRT is active. The PWRT delay allows the VDD to rise to an acceptable level. A Configuration bit, PWRTE, can disable (if set) or enable (if cleared or programmed) the Power-up Timer. The Power-up Timer should be enabled when Brown-out Reset is enabled, although it is not required.

The Power-up Timer delay will vary from chip-to-chip and vary due to:

- VDD variation
- Temperature variation
- Process variation

See DC parameters for details (**Section 23.0 "Electrical Specifications"**).

Note:	The Power-up Timer is enabled by the PWRTE bit in the Configuration Word.

3.4 Watchdog Timer (WDT)

The WDT has the following features:

- Shares an 8-bit prescaler with Timer0
- Time-out period is from 17 ms to 2.2 seconds, nominal
- Enabled by a Configuration bit

WDT is cleared under certain conditions described in Table 3-1.

3.4.1 WDT OSCILLATOR

The WDT derives its time base from 31 kHz internal oscillator.

Note:	When the Oscillator Start-up Timer (OST) is invoked, the WDT is held in Reset, because the WDT Ripple Counter is used by the OST to perform the oscillator delay count. When the OST count has expired, the WDT will begin counting (if enabled).

6.2.1 ANSELA REGISTER

The ANSELA register (Register 6-4) is used to configure the Input mode of an I/O pin to analog. Setting the appropriate ANSELA bit high will cause all digital reads on the pin to be read as '0' and allow analog functions on the pin to operate correctly.

The state of the ANSELA bits has no affect on digital output functions. A pin with TRIS clear and ANSEL set will still operate as a digital output, but the Input mode will be analog. This can cause unexpected behavior when executing read-modify-write instructions on the affected port.

REGISTER 6-4: ANSELA: PORTA ANALOG SELECT REGISTER

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	ANSA5	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0
bit 7							bit 0

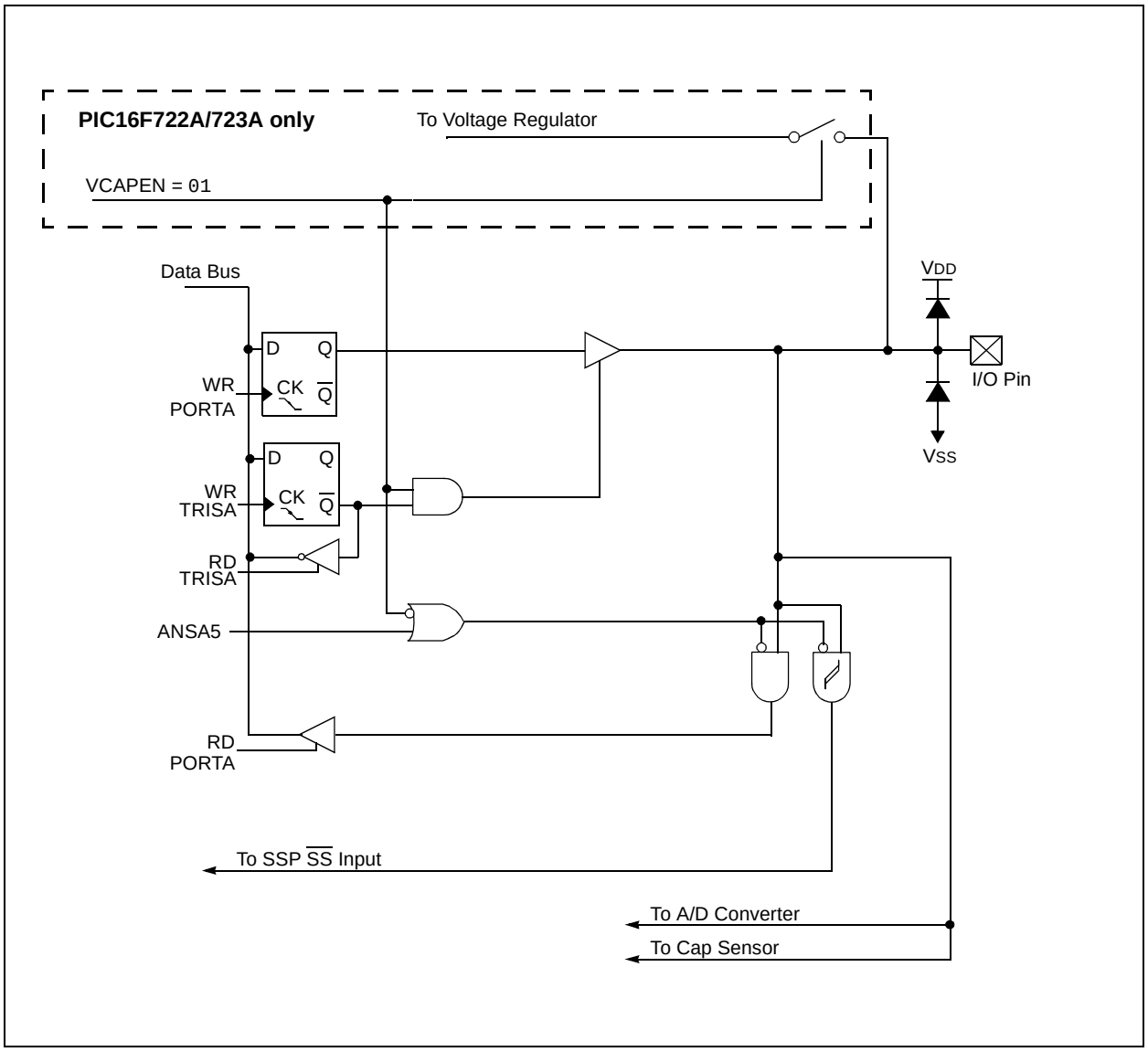
Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **ANSA<5:0>**: Analog Select between Analog or Digital Function on pins RA<5:0>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input(1). Digital input buffer disabled.

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

FIGURE 6-4: BLOCK DIAGRAM OF RA5



REGISTER 6-5: PORTB: PORTB REGISTER

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **RB<7:0>**: PORTB I/O Pin bits
1 = Port pin is > V_{IH}
0 = Port pin is < V_{IL}

REGISTER 6-6: TRISB: PORTB TRI-STATE REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **TRISB<7:0>:** PORTB Tri-State Control bits
1 = PORTB pin configured as an input (tri-stated)
0 = PORTB pin configured as an output

REGISTER 6-7: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
WPUB7	WPUB6	WPUB5	WPUB4	WPUB3	WPUB2	WPUB1	WPUB0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-0 **WPUB<7:0>**: Weak Pull-up Register bits
1 = Pull up enabled
0 = Pull up disabled

Note 1: Global $\overline{\text{RBPU}}$ bit of the OPTION register must be cleared for individual pull ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

FIGURE 6-15: BLOCK DIAGRAM OF RC2

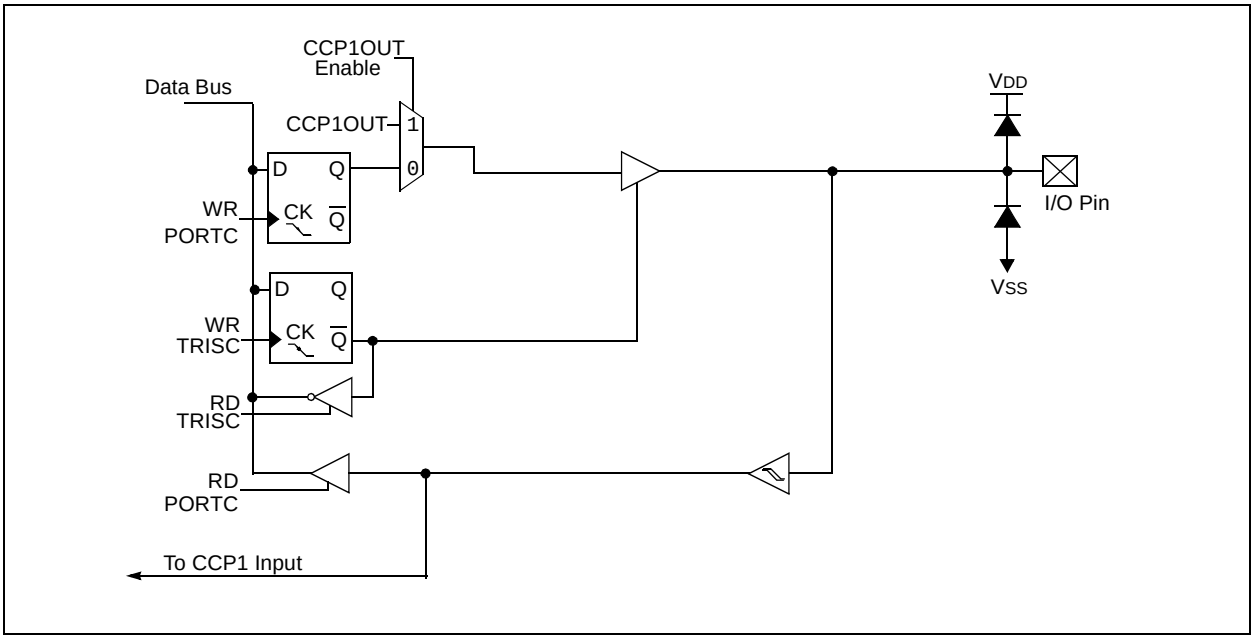
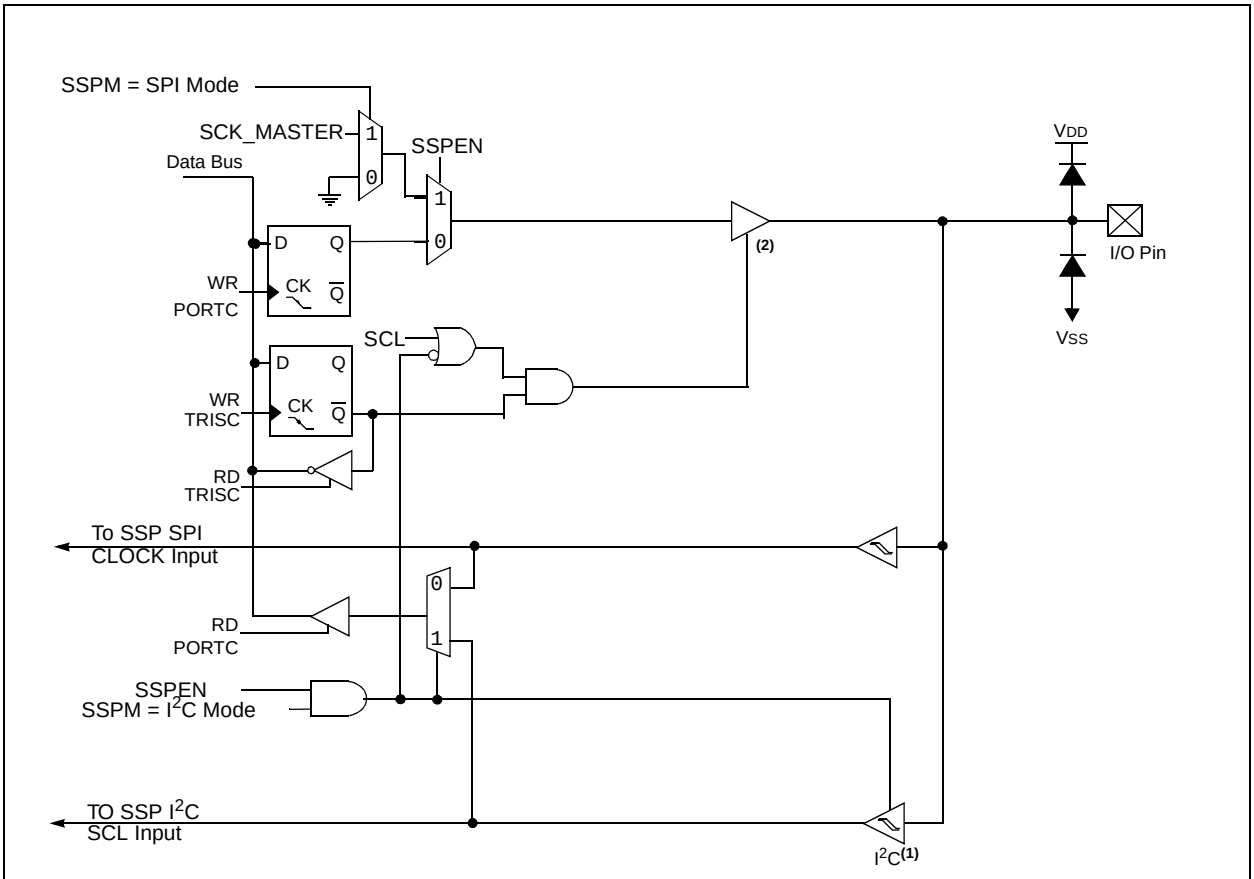
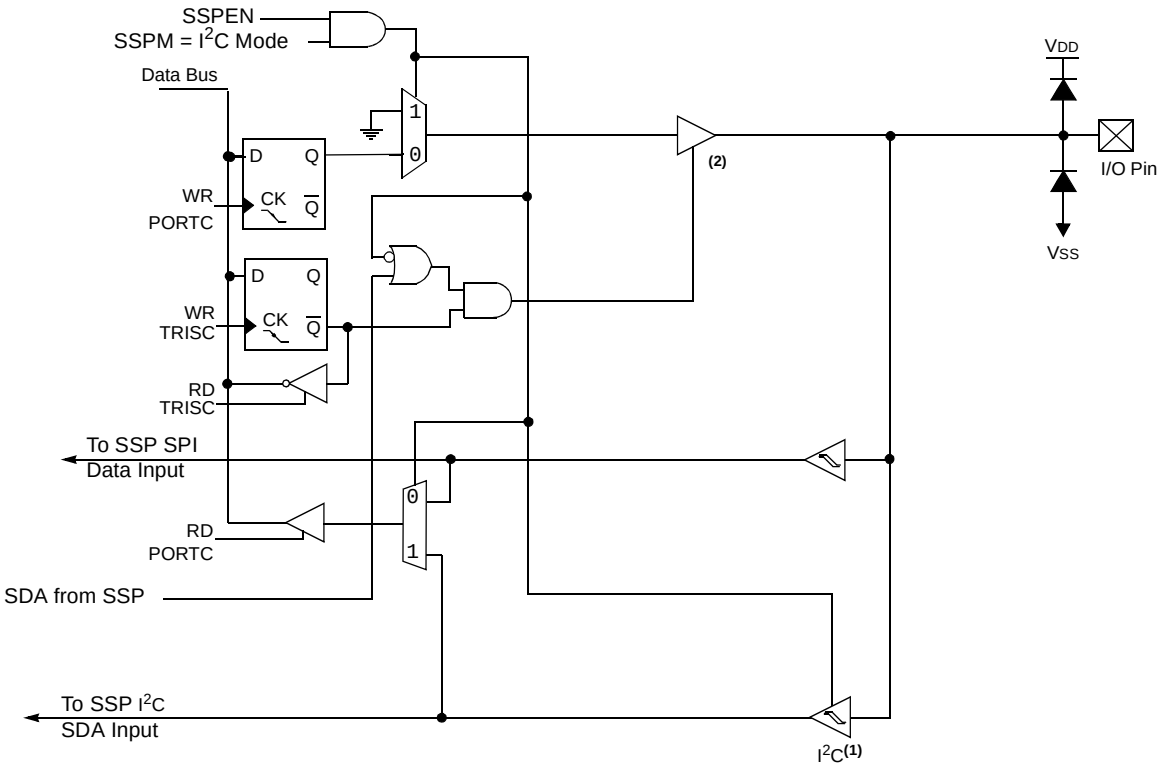


FIGURE 6-16: BLOCK DIAGRAM OF RC3



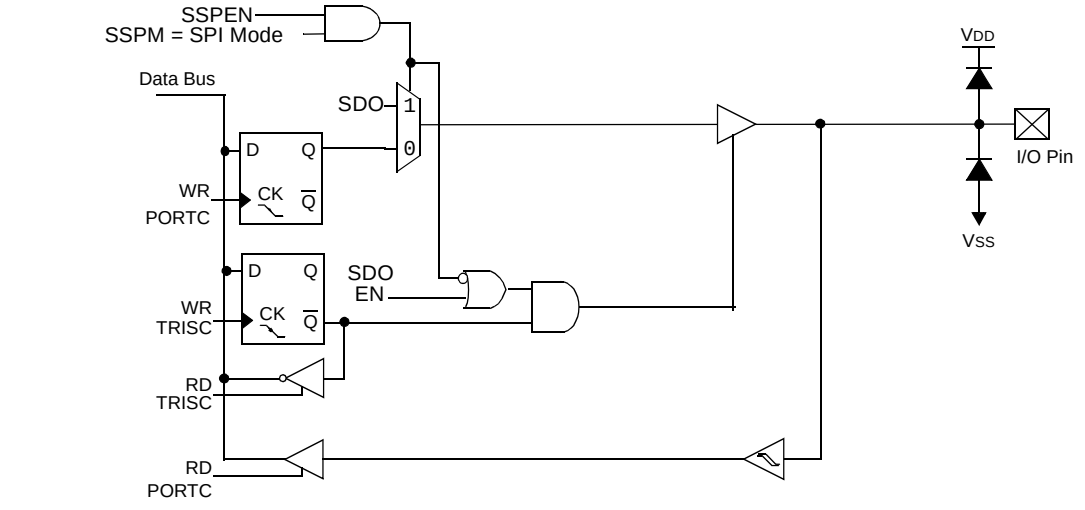
Note 1: I^2C Schmitt Trigger has special input levels.
2: I^2C Slew Rate limiting controlled by SMP bit of SSPSTAT register.

FIGURE 6-17: BLOCK DIAGRAM OF RC4



Note 1: I^2C Schmitt Trigger has special input levels.
2: I^2C Slew Rate limiting controlled by SMP bit of SSPSTAT register.

FIGURE 6-18: BLOCK DIAGRAM OF RC5



8.0 DEVICE CONFIGURATION

Device configuration consists of Configuration Word 1 and Configuration Word 2 registers, code protection and device ID.

8.1 Configuration Words

There are several Configuration Word bits that allow different oscillator and memory protection options. These are implemented as Configuration Word 1 register at 2007h and Configuration Word 2 register at 2008h. These registers are only accessible during programming.

REGISTER 8-1: CONFIG1: CONFIGURATION WORD REGISTER 1

R/P-1	R/P-1	U-1(4)	R/P-1	R/P-1	R/P-1
$\overline{\text{DEBUG}}$	PLLEN	—	BORV	BOREN1	BOREN0
bit 13					bit 8

U-1(4)	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
—	$\overline{\text{CP}}$	MCLRE	$\overline{\text{PWRTE}}$	WDTE	FOSC2	FOSC1	FOSC0
bit 7							bit 0

Legend:	P = Programmable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 13 **$\overline{\text{DEBUG}}$:** In-Circuit Debugger Mode bit
1 = In-circuit debugger disabled, RB6/ICSPCLK and RB7/ICSPDAT are general purpose I/O pins
0 = In-circuit debugger enabled, RB6/ICSPCLK and RB7/ICSPDAT are dedicated to the debugger

bit 12 **PLLEN:** INTOSC PLL Enable bit
0 = INTOSC frequency is 500 kHz
1 = INTOSC frequency is 16 MHz (32x)

bit 11 **Unimplemented:** Read as ‘1’

bit 10 **BORV:** Brown-out Reset Voltage selection bit
0 = Brown-out Reset Voltage (V_{BOR}) set to 2.5 V nominal
1 = Brown-out Reset Voltage (V_{BOR}) set to 1.9 V nominal

bit 9-8 **BOREN<1:0>:** Brown-out Reset Selection bits(1)
0x = BOR disabled (preconditioned state)
10 = BOR enabled during operation and disabled in Sleep
11 = BOR enabled

bit 7 **Unimplemented:** Read as ‘1’

bit 6 **$\overline{\text{CP}}$:** Code Protection bit(2)
1 = Program memory code protection is disabled
0 = Program memory code protection is enabled

bit 5 **MCLRE:** RE3/$\overline{\text{MCLR}}$ Pin Function Select bit(3)
1 = RE3/$\overline{\text{MCLR}}$ pin function is $\overline{\text{MCLR}}$
0 = RE3/$\overline{\text{MCLR}}$ pin function is digital input, $\overline{\text{MCLR}}$ internally tied to V_{DD}

bit 4 **$\overline{\text{PWRTE}}$:** Power-up Timer Enable bit
1 = PWRT disabled
0 = PWRT enabled

bit 3 **WDTE:** Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire program memory will be erased when the code protection is turned off.
3: When $\overline{\text{MCLR}}$ is asserted in INTOSC or RC mode, the internal clock oscillator is disabled.
4: MPLAB® X IDE masks unimplemented Configuration bits to ‘0’.

TABLE 12-2: WDT/TIMER1 GATE INTERACTION

WDTE	TMR1GE = 1 and T1GSS = 11	WDT Oscillator Enable	WDT Reset	Wake-up	WDT Available for T1G Source
1	N	Y	Y	Y	N
1	Y	Y	Y	Y	Y
0	Y	Y	N	N	Y
0	N	N	N	N	N

12.6.3 TIMER1 GATE TOGGLE MODE

When Timer1 Gate Toggle mode is enabled, it is possible to measure the full-cycle length of a Timer1 gate signal, as opposed to the duration of a single level pulse.

The Timer1 gate source is routed through a flip-flop that changes state on every incrementing edge of the signal. See Figure 12-5 for timing details.

Timer1 Gate Toggle mode is enabled by setting the T1GTM bit of the T1GCON register. When the T1GTM bit is cleared, the flip-flop is cleared and held clear. This is necessary in order to control which edge is measured.

Note:	Enabling Toggle mode at the same time as changing the gate polarity may result in indeterminate operation.

12.6.4 TIMER1 GATE SINGLE-PULSE MODE

When Timer1 Gate Single-Pulse mode is enabled, it is possible to capture a single pulse gate event. Timer1 Gate Single-Pulse mode is first enabled by setting the T1GSPM bit in the T1GCON register. Next, the T1GGO/$\overline{\text{DONE}}$ bit in the T1GCON register must be set. The Timer1 will be fully enabled on the next incrementing edge. On the next trailing edge of the pulse, the T1GGO/$\overline{\text{DONE}}$ bit will automatically be cleared. No other gate events will be allowed to increment Timer1 until the T1GGO/$\overline{\text{DONE}}$ bit is once again set in software.

Clearing the T1GSPM bit of the T1GCON register will also clear the T1GGO/$\overline{\text{DONE}}$ bit. See Figure 12-6 for timing details.

Enabling the Toggle mode and the Single-Pulse mode simultaneously will permit both sections to work together. This allows the cycle times on the Timer1 gate source to be measured. See Figure 12-7 for timing details.

12.6.5 TIMER1 GATE VALUE STATUS

When Timer1 gate value status is utilized, it is possible to read the most current level of the gate control value. The value is stored in the T1GVAL bit in the T1GCON register. The T1GVAL bit is valid even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

12.6.6 TIMER1 GATE EVENT INTERRUPT

When Timer1 gate event interrupt is enabled, it is possible to generate an interrupt upon the completion of a gate event. When the falling edge of T1GVAL occurs, the TMR1GIF flag bit in the PIR1 register will be set. If the TMR1GIE bit in the PIE1 register is set, then an interrupt will be recognized.

The TMR1GIF flag bit operates even when the Timer1 gate is not enabled (TMR1GE bit is cleared).

12.11 Timer1 Control Register

The Timer1 Control register (T1CON), shown in Register 12-1, is used to control Timer1 and select the various features of the Timer1 module.

REGISTER 12-1: T1CON: TIMER1 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0
TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 **TMR1CS<1:0>:** Timer1 Clock Source Select bits
- 11 = Timer1 clock source is Capacitive Sensing Oscillator (CAPOSC)
- 10 = Timer1 clock source is pin or oscillator:
  - If T1OSCEN = 0:
  - External clock from T1CKI pin (on the rising edge)
  - If T1OSCEN = 1:
  - Crystal oscillator on T1OSI/T1OSO pins
- 01 = Timer1 clock source is system clock (FOSC)
- 00 = Timer1 clock source is instruction clock (FOSC/4)

bit 5-4 **T1CKPS<1:0>:** Timer1 Input Clock Prescale Select bits
- 11 = 1:8 Prescale value
- 10 = 1:4 Prescale value
- 01 = 1:2 Prescale value
- 00 = 1:1 Prescale value

bit 3 **T1OSCEN:** LP Oscillator Enable Control bit
- 1 = Dedicated Timer1 oscillator circuit enabled
- 0 = Dedicated Timer1 oscillator circuit disabled

bit 2 **T1SYNC:** Timer1 External Clock Input Synchronization Control bit

TMR1CS<1:0> = 1X
- 1 = Do not synchronize external clock input
- 0 = Synchronize external clock input with system clock (FOSC)

TMR1CS<1:0> = 0X

This bit is ignored. Timer1 uses the internal clock when TMR1CS<1:0> = 1X.

bit 1 **Unimplemented:** Read as '0'

bit 0 **TMR1ON:** Timer1 On bit
- 1 = Enables Timer1
- 0 = Stops Timer1 (Clears Timer1 gate flip-flop)

19.0 POWER-DOWN MODE (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If the Watchdog Timer is enabled:

- WDT will be cleared but keeps running.
- $\overline{PD}$ bit of the STATUS register is cleared.
- $\overline{TO}$ bit of the STATUS register is set.
- Oscillator driver is turned off.
- Timer1 oscillator is unaffected
- I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).

For lowest current consumption in this mode, all I/O pins should be either at V_{DD} or V_{SS}, with no external circuitry drawing current from the I/O pin. I/O pins that are high-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The T0CKI input should also be at V_{DD} or V_{SS} for lowest current consumption. The contribution from on-chip pull ups on PORTB should be considered.

The $\overline{MCLR}$ pin must be at a logic high level when external $\overline{MCLR}$ is enabled.

Note:	A Reset generated by a WDT time out does not drive $\overline{MCLR}$ pin low.

19.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin.
2. Watchdog Timer wake-up (if WDT was enabled).
3. Interrupt from RB0/INT pin, PORTB change or a peripheral interrupt.

The first event will cause a device Reset. The two latter events are considered a continuation of program execution. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register can be used to determine the cause of device Reset. The $\overline{PD}$ bit, which is set on power-up, is cleared when Sleep is invoked. $\overline{TO}$ bit is cleared if WDT wake-up occurred.

The following peripheral interrupts can wake the device from Sleep:

1. TMR1 Interrupt. Timer1 must be operating as an asynchronous counter.
2. USART Receive Interrupt (Synchronous Slave mode only)
3. A/D conversion (when A/D clock source is RC)
4. Interrupt-on-change
5. External Interrupt from INT pin
6. Capture event on CCP1 or CCP2
7. SSP Interrupt in SPI or I^2C Slave mode

Other peripherals cannot generate interrupts since during Sleep, no on-chip clocks are present.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction, then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

Note:	If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from Sleep. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

SUBWF **Subtract W from f**

Syntax: [*label*] SUBWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - (W) → (destination)

Status Affected: C, DC, Z

Description: Subtract (2's complement method) W register from register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f.

C = 0	W > f
C = 1	W ≤ f
DC = 0	W<3:0> > f<3:0>
DC = 1	W<3:0> ≤ f<3:0>

SWAPF **Swap Nibbles in f**

Syntax: [*label*] SWAPF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f<3:0>) → (destination<7:4>),
(f<7:4>) → (destination<3:0>)

Status Affected: None

Description: The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in register 'f'.

XORLW **Exclusive OR literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Description: The contents of the W register are XOR'ed with the 8-bit literal 'k'. The result is placed in the W register.

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (destination)

Status Affected: Z

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

23.1 DC Characteristics: PIC16(L)F722A/723A-I/E (Industrial, Extended)

PIC16LF722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722A/723A			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**					
		PIC16LF722A/723A	1.8 1.8 2.3 2.5	— — — —	3.6 3.6 3.6 3.6	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D001		**PIC16F722A/723A**	1.8 1.8 2.3 2.5	— — — —	5.5 5.5 5.5 5.5	V V V V	FOSC ≤ 16 MHz: HFINTOSC, EC FOSC ≤ 4 MHz FOSC ≤ 20 MHz, EC FOSC ≤ 20 MHz, HS
D002*	VDR	**RAM Data Retention Voltage(1)**					
		PIC16LF722A/723A	1.5	—	—	V	Device in Sleep mode
D002*		**PIC16F722A/723A**	1.7	—	—	V	Device in Sleep mode
	VPOR*	**Power-on Reset Release Voltage**	—	1.6	—	V	
	VPORR*	**Power-on Reset Rearm Voltage**					
		PIC16LF722A/723A	—	0.8	—	V	Device in Sleep mode
		PIC16F722A/723A	—	1.7	—	V	Device in Sleep mode
D003	VFVR	**Fixed Voltage Reference Voltage, Initial Accuracy**	-5.5 -5.5 -5.5	— — —	5.5 5.5 5.5	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 85°C
			-6 -6 -6	— — —	6 6 6	% % %	VFVR = 1.024V, VDD ≥ 2.5V VFVR = 2.048V, VDD ≥ 2.5V VFVR = 4.096V, VDD ≥ 4.75V; -40 ≤ TA ≤ 125°C
D004*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05	—	—	V/ms	See **Section 3.2 "Power-on Reset (POR)"** for details.

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

23.2 DC Characteristics: PIC16(L)F722A/723A-I/E (Industrial, Extended) (Continued)

PIC16LF722A/723A			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F722A/723A			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D014		—	290	330	µA	1.8	FOSC = 4 MHz EC Oscillator mode
		—	460	500	µA	3.0	
D014		—	300	430	µA	1.8	FOSC = 4 MHz EC Oscillator mode **(Note 5)**
		—	450	655	µA	3.0	
		—	500	730	µA	5.0	
D015		—	100	130	µA	1.8	FOSC = 500 kHz MFINTOSC mode
		—	120	150	µA	3.0	
D015		—	115	195	µA	1.8	FOSC = 500 kHz MFINTOSC mode **(Note 5)**
		—	135	200	µA	3.0	
		—	150	220	µA	5.0	
D016		—	650	800	µA	1.8	FOSC = 8 MHz HFINTOSC mode
		—	1000	1200	µA	3.0	
D016		—	625	850	µA	1.8	FOSC = 8 MHz HFINTOSC mode **(Note 5)**
		—	1000	1200	µA	3.0	
		—	1100	1500	µA	5.0	
D017		—	1.0	1.2	mA	1.8	FOSC = 16 MHz HFINTOSC mode
		—	1.5	1.85	mA	3.0	
D017		—	1	1.2	mA	1.8	FOSC = 16 MHz HFINTOSC mode **(Note 5)**
		—	1.5	1.7	mA	3.0	
		—	1.7	2.1	mA	5.0	
D018		—	210	240	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 3, Note 5)**
		—	340	380	µA	3.0	
D018		—	225	320	µA	1.8	FOSC = 4 MHz EXTRC mode **(Note 3, Note 5)**
		—	360	445	µA	3.0	
		—	410	650	µA	5.0	
D019		—	1.6	1.9	mA	3.0	FOSC = 20 MHz HS Oscillator mode
		—	2.0	2.8	mA	3.6	
D019		—	1.6	2	mA	3.0	FOSC = 20 MHz HS Oscillator mode **(Note 5)**
		—	1.9	3.2	mA	5.0	

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

4: FVR and BOR are disabled.

5: 0.1 µF capacitor on VCAP (RA0).

23.7 AC Characteristics: PIC16F722A/723A-I/E

FIGURE 23-3: CLOCK TIMING

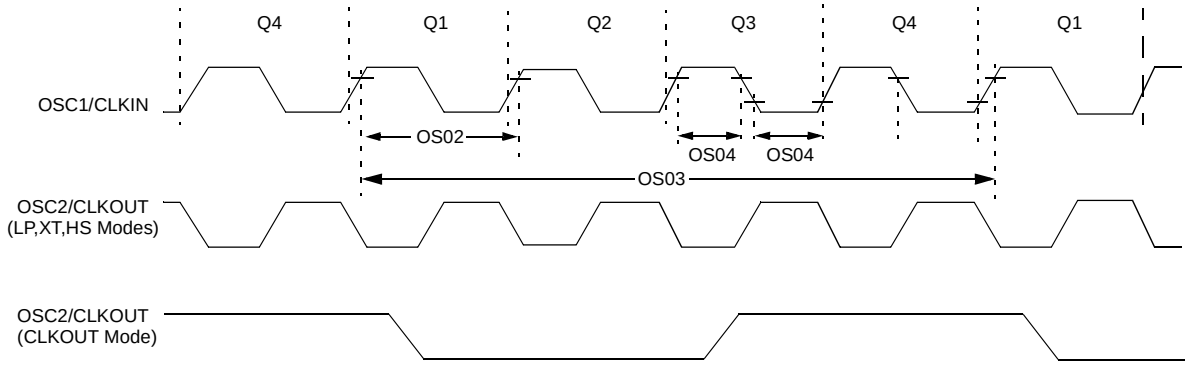
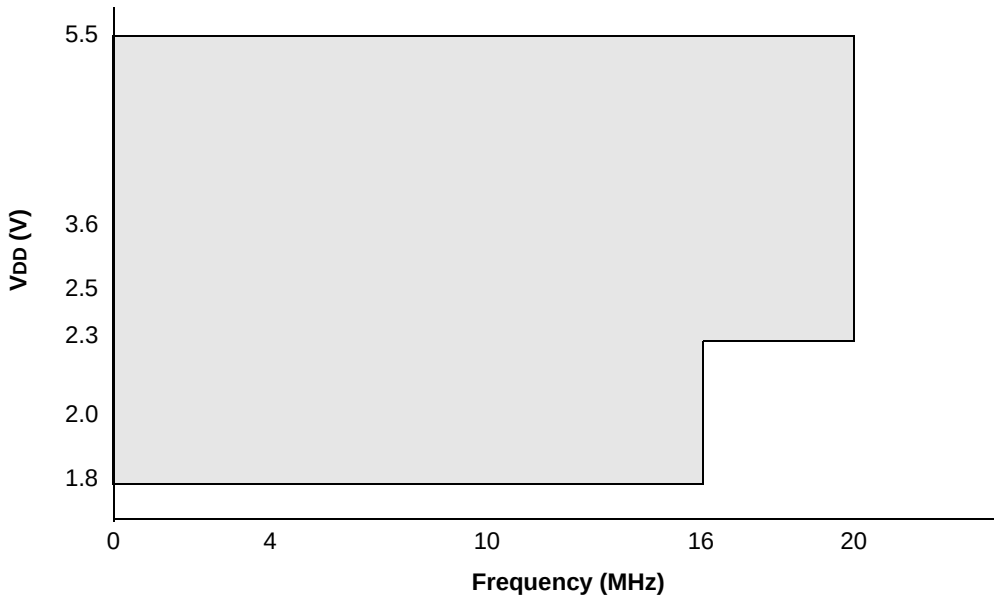


FIGURE 23-4: PIC16F722A/723A VOLTAGE FREQUENCY GRAPH, -40°C ≤ TA ≤ +125°C



Note 1: The shaded region indicates the permissible combinations of voltage and frequency.
2: Refer to Table 23-1 for each Oscillator mode's supported frequencies.

TABLE 23-7: PIC16F722A/723A A/D CONVERTER (ADC) CHARACTERISTICS:

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD01	NR	Resolution	—	—	8	bit	
AD02	EIL	Integral Error	—	—	±1.7	LSb	VREF = 3.0V
AD03	EDL	Differential Error	—	—	±1	LSb	No missing codes VREF = 3.0V
AD04	EOFF	Offset Error	—	—	±2.2	LSb	VREF = 3.0V
AD05	EGN	Gain Error	—	—	±1.5	LSb	VREF = 3.0V
AD06	VREF	Reference Voltage(3)	1.8	—	VDD	V	
AD07	VAIN	Full-Scale Range	VSS	—	VREF	V	
AD08	ZAIN	Recommended Impedance of Analog Voltage Source	—	—	50	kΩ	Can go higher if external 0.01µF capacitor is present on input pin.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Total Absolute Error includes integral, differential, offset and gain errors.

2: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

3: When ADC is off, it will not consume any current other than leakage current. The power-down current specification includes any such leakage from the ADC module.

TABLE 23-8: PIC16F722A/723A A/D CONVERSION REQUIREMENTS

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
AD130*	TAD	A/D Clock Period	1.0	—	9.0	µs	TOSC-based
		A/D Internal RC Oscillator Period	1.0	2.0	6.0	µs	ADCS<1:0> = 11 (ADRC mode)
AD131	TCNV	Conversion Time (not including Acquisition Time)(1)	—	10.5	—	TAD	Set GO/$\overline{\text{DONE}}$ bit to conversion complete
AD132*	TACQ	Acquisition Time	—	1.0	—	µs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The ADRES register may be read on the following TCY cycle.

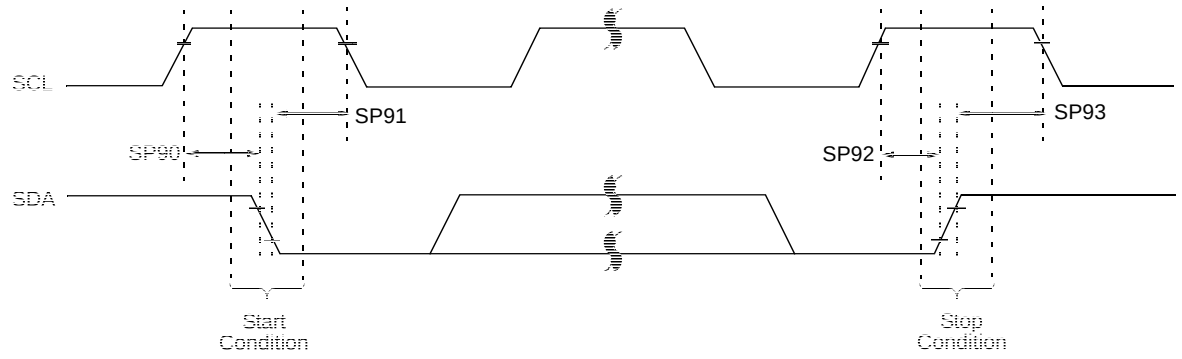
TABLE 23-11: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input		Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDO data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance		10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5 Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 23-20: I^2C BUS START/STOP BITS TIMING



Note: Refer to Figure 23-2 for load conditions.

FIGURE 24-2: PIC16LF722A/723A MAXIMUM IDD vs. FOSC OVER VDD, EC MODE

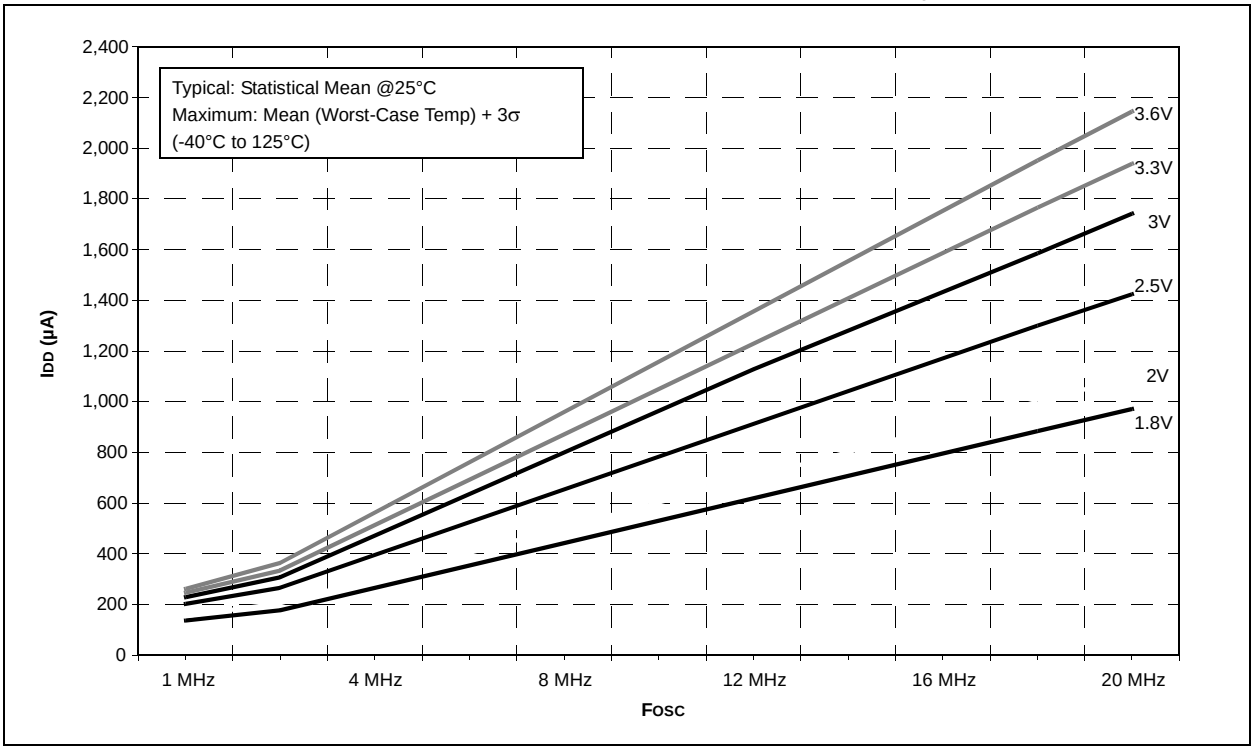


FIGURE 24-3: PIC16F722A/723A TYPICAL IDD vs. FOSC OVER VDD, EC MODE, VCAP = 0.1µF

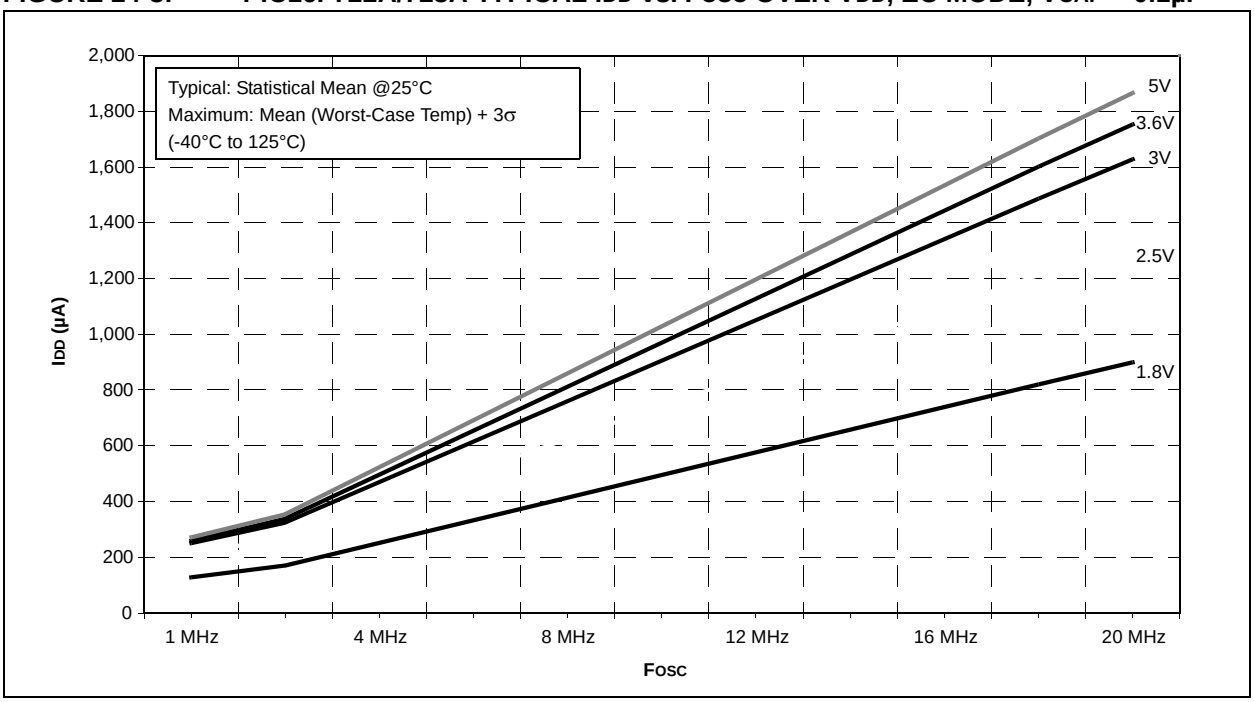


FIGURE 24-54: VOH vs. IOH OVER TEMPERATURE, VDD = 1.8V

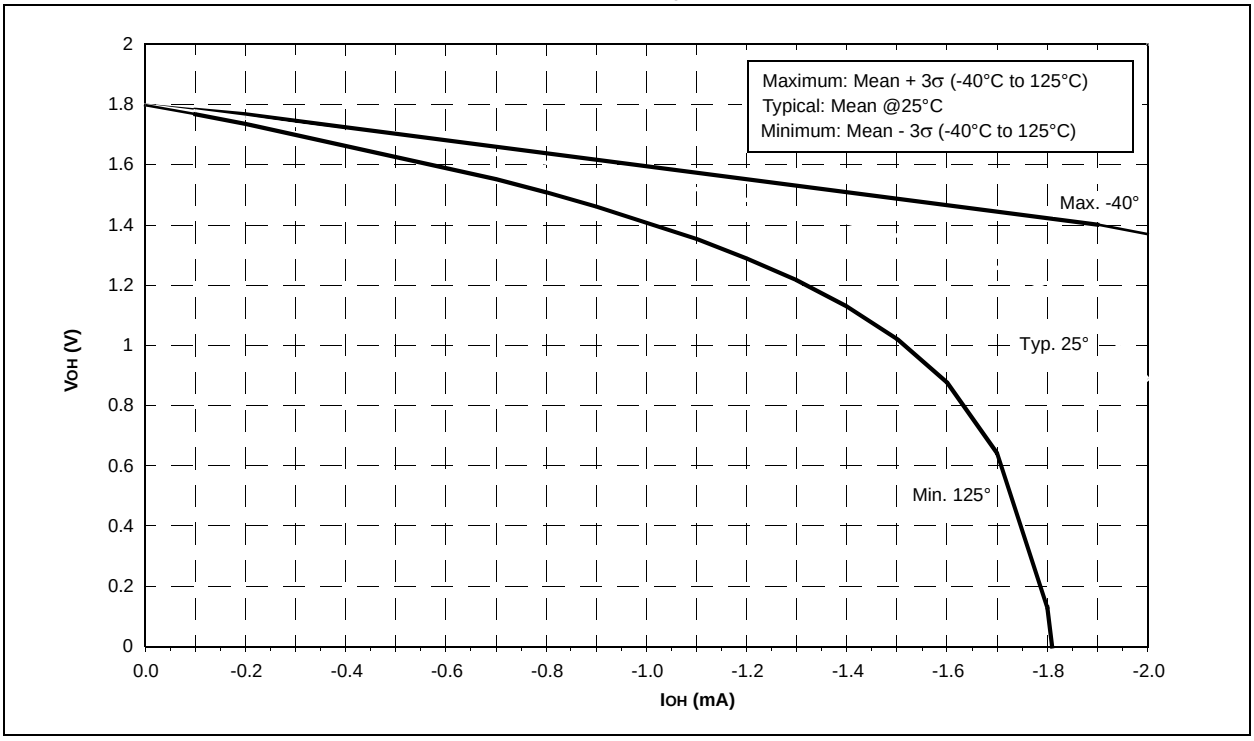
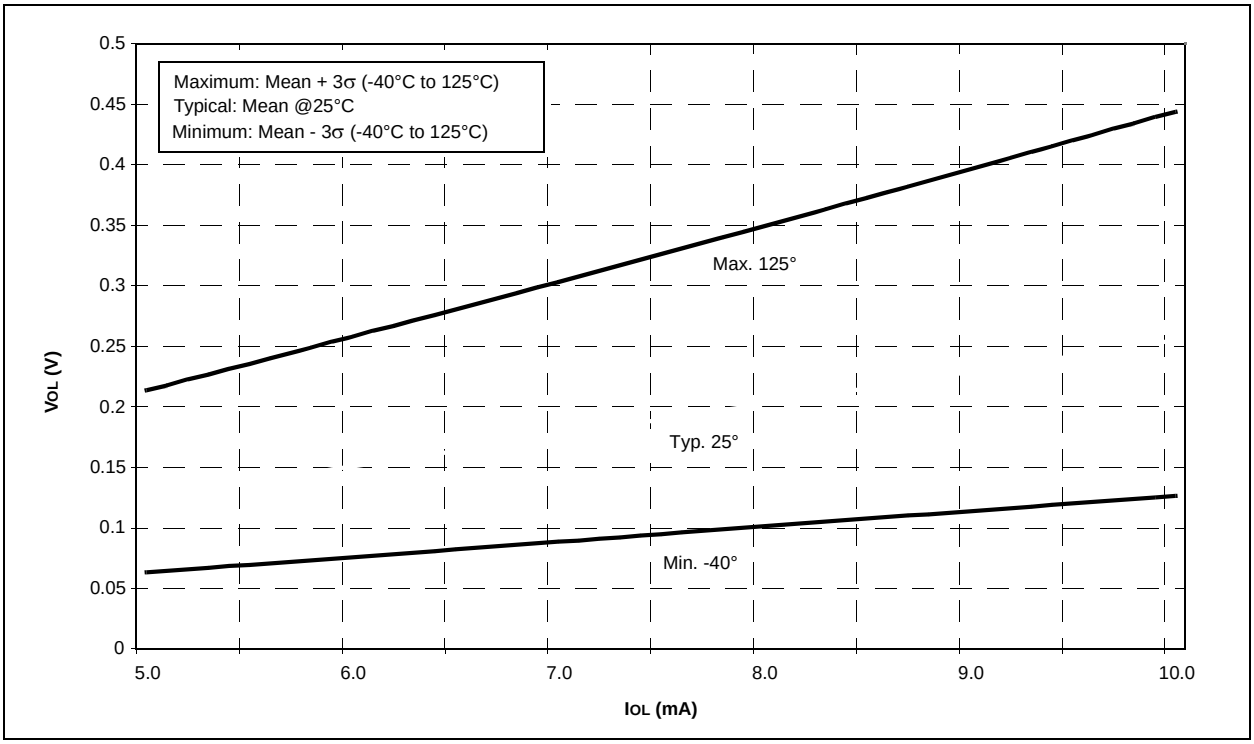
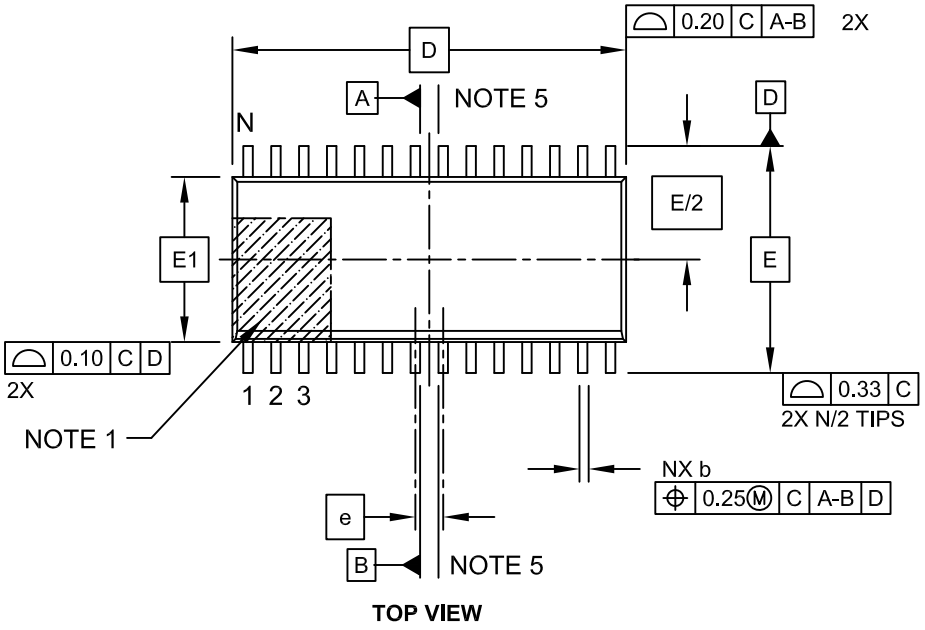


FIGURE 24-55: VOL vs. IOL OVER TEMPERATURE, VDD = 5.5V

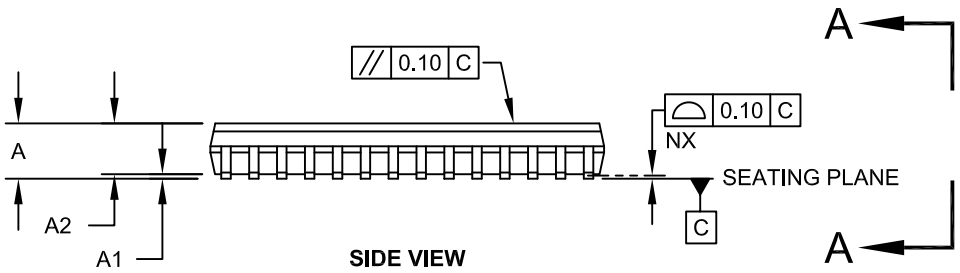


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

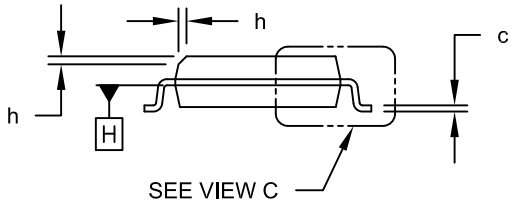
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW



VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
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